

**Insulation panel made of expanded phenolic resin foam (PF).
Suitable for the TERMOK8 FENOLICO system.**

DESCRIPTION

Rigid panel for thermal insulation made of expanded phenolic resin foam (PF), free from CFCs, HCFCs, and HFCs.

Compliant with UNI EN 13166 and supplied with a Certificate of Conformity.

Faced on both sides with saturated glass veil, it is suitable for high thermal performance applications in the building sector.

The panels comply with the Minimum Environmental Criteria (CAM).



MAIN PROPERTIES

- Ease of installation;
- High thermal insulation;
- Reduced thickness.

TECHNICAL DATA

Resistance to water vapour passage (EN 12086)	40
Specific heat (EN 10456)	1750 J/kgK
Compression stress at 10% deformation (EN 826)	≥ 150 kPa
Tensile strength perpendicular to the faces (EN 1607)	≥ 80 kPa
Thickness tolerance (EN 823)	± 2 mm for thicknesses from 20 to 40 mm +2/-3 mm for thicknesses from 50 to 90 mm +2/-5 mm for thicknesses from 100 to 160 mm
Short-term water absorption (EN 29767)	≤ 0,75 Kg/m ²
Thermal conductivity (λ) (EN 12667)	0.021 W/mK for thicknesses from 20 to 70 mm 0.019 W/mK for thicknesses from 80 to 160 mm
Reaction to fire (EN 13501-1)	B- s1, d0

CHARACTERISTICS

Size slabs	120 cm x 60 cm
Thickness	2, 3, 4, 5, 6, 7, 8, 9, 10, 12, 14, 16 cm

APPLICATION

Application Procedure:

Compensate any curvature of the boards by applying varying thicknesses of adhesive behind the boards, up to a maximum of 15 mm.

STORAGE

Storage:

Store the packages raised off the ground. Do not leave the packages exposed to weather, moisture or sunlight. Do not leave the boards for extended periods in conditions or positions that could compromise their flatness.

TECHNOLOGIES/CERTIFICATIONS

